



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL31A226MOCLFNC

• Product : Multi-layer Ceramic Capacitor • Descriptiont : CAP, 22 µF, 16V, ±20%, X5R, 1206

## A. Samsung Part Number

<u>CL</u> <u>31</u> <u>A</u> <u>226</u> <u>M</u> <u>O</u> <u>C</u> <u>L</u> <u>F</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor						
2	Size	1206 (inch co	ode) L: 3.2	± 0.2 mm	W:	1.6	± 0.2	mm
			8	Thickness division		Low profile		
3	Dielectric	X5R		Inner electrode		Ni		
4	Capacitance	<b>22</b> μF		Termination		Cu		
⑤	Capacitance	±20 %		Plating		Sn 10	0%	(Pb Free)
	tolerance		9	Product		Produ	ct for P	OWER application
6	Rated Voltage	16 V	10	Special		Reserved for future use		
7	Thickness	0.85 ± 0.1	mm 🕦	Packaging		Cardb	oard T	ype, 7" reel

## **B. Samsung Reliability Test and Judgement condition**

	Performance	Test condition					
Capacitance	Within specified tolerance	120Hz ±20% 0.5±0.1Vrms					
Tan δ (DF)	0.1 max.						
Insulation	10,000Mohm or 100Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	250% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	X5R						
Characteristics	(From -55℃ to 85℃, Capacitance change should be within ±15%)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120 ℃ for 10~30sec.)					
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.						

	Performance	Test condition				
Vibration Test	Capacitance change: within ±5%	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)				
		2hours × 3 direction (x, y, z)				
Moisture	Capacitance change: within ±12.5%	With rated voltage				
Resistance	Tan δ: 0.2 max	40±2℃, 90~95%RH, 500+12/-0hrs				
	IR: 12.5M\\overline{\mu}\cdot \mu \text{F or Over}					
High Temperature	Capacitance change: within ±12.5%	With 100% of the rated voltage				
Resistance	Tan δ : 0.2 max	Max. operating temperature				
	IR: 25MΩ·μF or Over					
		1000+48/-0hrs				
Temperature	Capacitance change: within ±7.5%	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C				
		$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}\mathrm{C}$				
		5 cycle test				

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}\text{C}$  , 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.